Photocouplers GaAlAs Infrared LED & Photo Diode

TLP3910

1. Applications

- Factory Automation (FA)
- Measuring Instruments
- MOSFET Gate Drivers
- Programmable Logic Controllers (PLCs)

2. General

The TLP3910 is a photocoupler in the SO6L package that consists of an infrared light emitting diode optically coupled to a photodiode array. The photodiodes are connected in series, making the TLP3910 suitable for MOS gate drive applications.

Also, to improve V_{OC} , TLP3910 is suitable for driving Super Junction Structure (SJ) MOSFETs.

3. Features

- (1) Open voltage: 14 V (min)
- (2) Short current: $12 \ \mu A \ (min)$
- (3) Isolation voltage: 5000 Vrms (min)
- (4) Safety standards

UL-recognized: UL 1577, File No.E67349

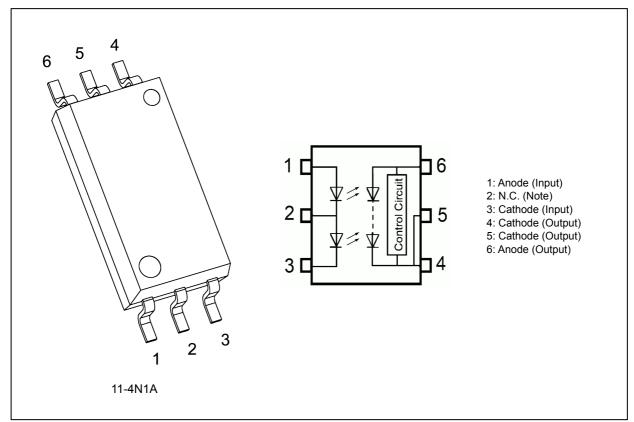
- cUL-recognized: CSA Component Acceptance Service No.5A File No.E67349
- VDE-approved: EN 60747-5-5 (Note 1)
- Note 1: When a VDE approved type is needed, please designate the Option (D4).

Table Short-Circuit Current (Note) (Unless otherwise specified, T _a = 25 °C)	Table	Short-Circuit Current (Note) (Unless	otherwise specified, $T_a = 25 $ °C)
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Rank	I _{SC} Rank Marking	Test Condition	Short-Circuit Current I _{SC} (min)	Unit
C20	C2	I _F = 10 mA	20	μA
None	C2, Blank	I _F = 10 mA	12	

Note: Specify both the part number and a rank in this format when ordering. Example: TLP3910(C20) For safety standard certification, however, specify the part number alone. Example: TLP3910(C20,E \rightarrow TLP3910

4. Packaging and Pin Assignment



Note: Input side is considerd 2 LEDs serial connection.(i.e. Foward mean pin 1 to 3, Reverse mean pin 3 to 1.) Don't connect anything to pin 2.

5. Mechanical Parameters

Characteristics	Min	Unit
Creepage distances	8.0	mm
Clearance	8.0	
Internal isolation thickness	0.4	

6. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25$ °C)

	Characteristics		Symbol	Note	Rating	Unit
LED	Input forward current		I _F	(Note 1)	30	mA
	Input forward current	(T _a = 125 °C)		(Note 1)	10	
	Input forward current derating	(T _a ≥ 100 °C)	$\Delta I_F / \Delta T_a$	(Note 1)	-0.8	mA/°C
	Input power dissipation		PD	(Note 1)	100	mW
	Input power dissipation derating	$(T_a \ge 100 \ ^\circ C)$	$\Delta P_D / \Delta T_a$	(Note 1)	-2.86	mW/°C
	Input reverse voltage		V _R	(Note 2)	10	V
Detector	Output forward current		I _{FD}		60	μA
	Output reverse voltage		V _{RD}		20	V
	Output power dissipation	(-40 ≤T _a ≤ 125 °C)	Po		1.5	mW
Common	Operating temperature		T _{opr}		-40 to 125	°C
	Storage temperature		T _{stg}		-55 to 135	°C
	Lead soldering temperature	(10 s)	T _{sol}		260	°C
	Isolation voltage	AC, 60 s, R.H. ≤ 60 %	BVS	(Note 3)	5000	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: I_F and P_D pin connection: Pin 1 to 3.

Note 2: V_R pin connection: Pin 3 to 1.

Note 3: This device is considered as a two-terminal device: Pins 1, 2 and 3 are shorted together, and pins 4, 5 and 6 are shorted together.

7. Recommended Operating Conditions (Note)

Characteristics	Symbol	Note	Min	Тур.	Max	Unit
Input forward current	١ _F	(Note 1)	_	12	15	mA
Operating temperature	T _{opr}		-25		100	°C

Note: The recommended operating conditions are given as a design guide necessary to obtain the intended performance of the device. Each parameter is an independent value. When creating a system design using this device, the electrical characteristics specified in this data sheet should also be considered.

Note 1: IF pin conection: Pin 1 to 3.(Pin 2 is N.C.)

8. Electrical Characteristics (Unless otherwise specified, T_a = 25 °C)

	Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
LED	Input forward voltage	V _F	(Note 1)	I _F = 10 mA	3	3.3	3.6	V
	Input reverse current	I _R	(Note 2)	V _R = 10 V		_	10	μA
	Input capacitance	Ct		V = 0 V, f = 1 MHz	_	23	_	pF

Note 1: VF and IF pin conection: Pin 1 to 3.(Pin 2 is N.C.) Note 2: VR and IR pin conection: Pin 3 to 1.(Pin 2 is N.C.)

9. Coupled Electrical Characteristics (Unless otherwise specified, $T_a = 25$ °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Trigger LED current	I _{FT}	(Note 1)	$V_{OC} \ge 10 \text{ V}$	_	0.5	3	mA
Open voltage	V _{oc}	(Note 1)	I _F = 10 mA	14	18	24	V
		(Note 1)	I _F = 10 mA, T _a = 125 °C	_	11	_	
		(Note 1)	I _F = 10 mA, T _a = -40 °C	_	22	—	
Short-circuit current	I _{SC}	(Note 1)	I _F = 10 mA	12	34	70	μA
		(Note 1)	I _F = 10 mA, T _a = 125 °C	_	26	_	μA

Note 1: IF and IFT pin conection: Pin 1 to 3.(Pin 2 is N.C.)

10. Isolation Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Total capacitance (input to output)	CS	(Note 1)	V _S = 0 V, f = 1 MHz		0.8	—	pF
Isolation resistance	R _S	(Note 1)	V_S = 500 V, R.H. \leq 60 %	10 ¹²	10 ¹⁴	—	Ω
Isolation voltage	BVS	(Note 1)	AC, 60 s	5000	_		Vrms

Note 1: This device is considered as a two-terminal device: Pins 1, 2 and 3 are shorted together, and pins 4, 5 and 6 are shorted together.

11. Switching Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Turn-on time	t _{on}		I _F = 10 mA, C _L = 1000 pF	_	0.3	1.0	ms
Turn-off time	t _{off}		See Fig. 11.1.	_	0.1	0.5	

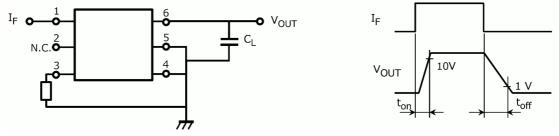
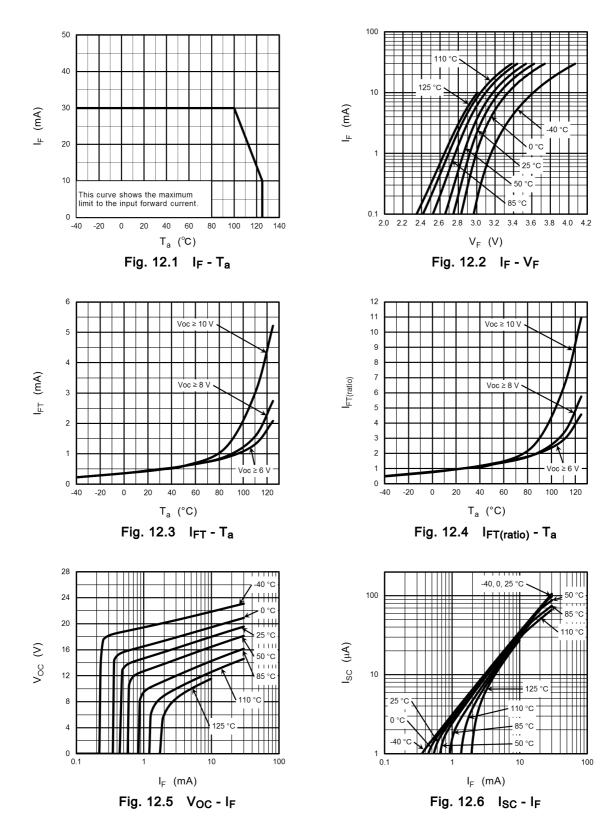


Fig. 11.1 Switching Time Test Circuit, Waveform

12. Characteristics Curves (Note)



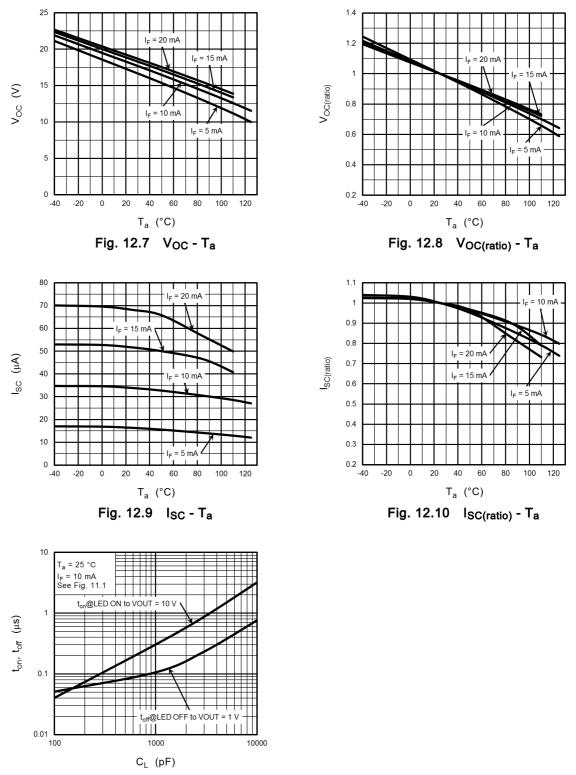


Fig. 12.11 ton, toff - CL

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

13. Soldering and Storage

13.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

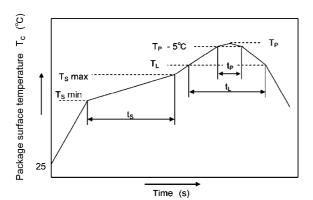
• When using soldering reflow.

The soldering temperature profile is based on the package surface temperature.

(See the figure shown below, which is based on the package surface temperature.)

Reflow soldering must be performed once or twice.

The mounting should be completed with the interval from the first to the last mountings being 2 weeks.



	Symbol	Min	Max	Unit
Preheat temperature	Ts	150	200	°C
Preheat time	ts	60	120	s
Ramp-up rate $(T_L \text{ to } T_P)$			3	°C/s
Liquidus temperature	TL	217 °		°C
Time above T _L	tL	60	150	s
Peak temperature	Τ _Ρ		260	°C
Time during which T_c is between (T_P-5) and T_P	t _P		30	s
Ramp-down rate $(T_P \text{ to } T_L)$			6	°C/s

Fig. 13.1.1 An example of a temperature profile when lead(Pb)-free solder is used

• When using soldering flow

Preheat the device at a temperature of 150 $^{\circ}$ C (package surface temperature) for 60 to 120 seconds. Mounting condition of 260 $^{\circ}$ C within 10 seconds is recommended.

Flow soldering must be performed once.

• When using soldering Iron

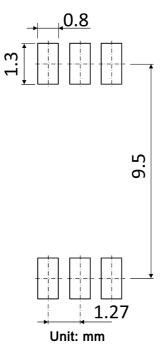
Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C

Heating by soldering iron must be done only once per lead.

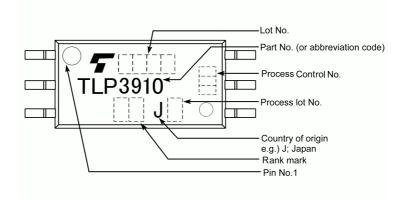
13.2. Precautions for General Storage

- Avoid storage locations where devices may be exposed to moisture or direct sunlight
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5 $^\circ C$ to 35 $^\circ C$ and 45 % to 75 %, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

14. Land Pattern Dimensions (for reference only)



15. Marking



16. EN 60747-5-5 Option (D4) Specification

- Part number: TLP3910 (Note 1)
- The following part naming conventions are used for the devices that have been qualified according to option (D4) of EN 60747.

Example: TLP3910(D4-TP,E

D4: EN 60747 option TP: Tape type E: [[G]]/RoHS COMPATIBLE **(Note 2)**

Note 1: Use TOSHIBA standard type number for safety standard application. e.g., TLP3910(D4-TP,E \rightarrow TLP3910

Note 2: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

Description	Symbol	Rating	Unit
Application classification			
for rated mains voltage \leq 600 Vrms for rated mains voltage \leq 1000 Vrms		I-IV I-III	_
Climatic classification		40 / 125 / 21	_
Pollution degree		2	_
Maximum operating insulation voltage	VIORM	1230	Vpeak
Input to output test voltage, Method A Vpr = 1.6 × VIORM, type and sample test tp = 10 s, partial discharge < 5 pC	Vpr	1970	Vpeak
Input to output test voltage, Method B Vpr =1.875 × VIORM, 100 % production test tp = 1 s, partial discharge < 5 pC	Vpr	2310	Vpeak
Highest permissible overvoltage (transient overvoltage, t _{pr} = 60 s)	VTR	8000	Vpeak
Safety limiting values (max. permissible ratings in case of fault, also refer to thermal derating curve) current (input current IF, P _{so} = 0) power (output or total power dissipation) temperature	lsi Pso Ts	300 700 150	mA mW °C
Insulation resistance $V_{IO} = 500 \text{ V}, \text{ T}_{a} = 25 ^{\circ}\text{C}$ $V_{IO} = 500 \text{ V}, \text{ T}_{a} = 100 ^{\circ}\text{C}$ $V_{IO} = 500 \text{ V}, \text{ T}_{a} = \text{ T}_{s}$	Rsi	≥ 10 ¹² ≥ 10 ¹¹ ≥ 10 ⁹	Ω

Fig. 16.1 EN 60747 Insulation Characteristics

Minimum creepage distance	Cr	8.0 mm
Minimum clearance	CI	8.0 mm
Minimum insulation thickness	ti	0.4 mm
Comparative tracking index	СТІ	500



Note: This photocoupler is suitable for **safe electrical isolation** only within the safety limit data. Maintenance of the safety data shall be ensured by means of protective circuits.

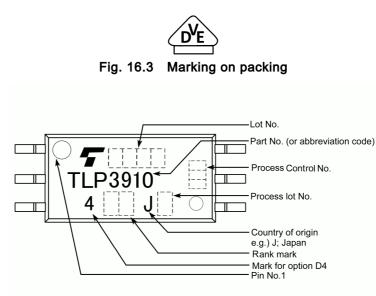
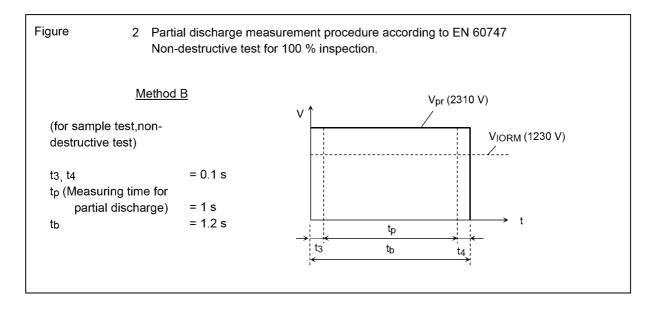
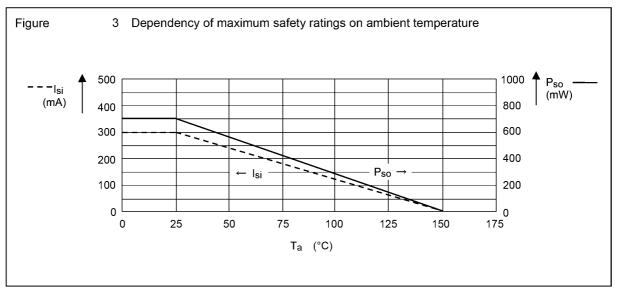


Fig. 16.4 Marking Example (Note)

Note: The above marking is applied to the photocouplers that have been qualified according to option (D4) of EN 60747.

5	-	asurement procedure according to EN 60747 ualification and sampling tests.
Method	<u>A</u>	VINITIAL (8 kV)
(for type and sampling t destructive tests)	ests,	V Vpr (1970 V)
t1, t2	= 1 to 10 s	VIORM (1230 V)
t3, t4	= 1 s	
tp (Measuring time for		
partial discharge)	= 10 s	$0 \xrightarrow{I} t \xrightarrow{I} t$
tb	= 12 s	t_3 t_p t_4
tini	= 60 s	t1 tini t2 tb







16.1. Ordering Information

When placing an order, please specify the part number, $I_{\rm SC}$ rank, tape type and quantity as shown in the following example.

Example) TLP3910(TP,E(O 1500pcs

Part number: TLP3910 Tape type: TP [[G]]/RoHS COMPATIBLE: E **(Note)** Domestic ID (Country / Region of origin: Japan): (O Quantity (must be a multiple of 1500): 1500pcs

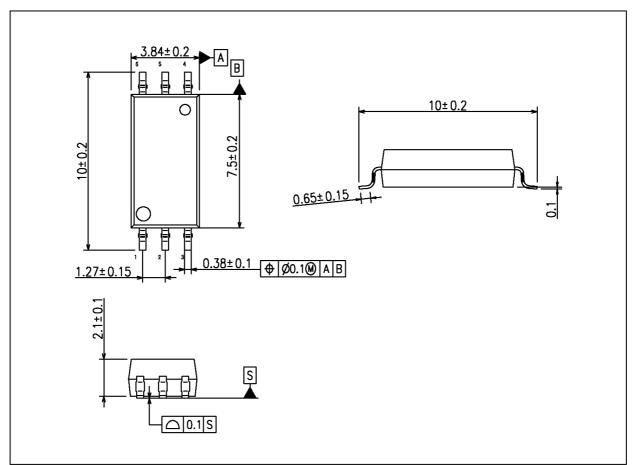
Note : Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility. RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the

restriction of the use of certain hazardous substances in electrical and electronic equipment.

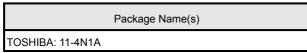
TLP3910

Package Dimensions

Unit: mm



Weight: 0.126 g (typ.)



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